

UNITED STATES DEPARTMENT OF COMMERCE

Patent and Trademark Offic

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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR		ATTORNEY DOCKET NO.		
09/069.668	04/29/9	8 AHN	К	303.466US1		
021186 MMC1/0509				EXAMINER		
021186 SCHWEGMAN.	LUNDBERG.	COUE	COLEMAN.W			
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH P.O. BOX 2938 MINNEAPOLIS MN 55402			ART UNIT			
			2823	ł		
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		•		05/09/01		

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner of Patents and Trademarks

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	- /	Application No.		Applicant(s)					
	Office Action Summary	09/069,668		AHN ET AL.					
	Office Action Summary	Examiner		Art Unit					
	P '~.	W. David Coleman	1	2823					
Period f	The MAILING DATE of this communication ap or Reply	ppears on the cover sh	t with the cor	respondence ad	dress				
THE - External control	MORTENED STATUTORY PERIOD FOR REF MAILING DATE OF THIS COMMUNICATION ensions of time may be available under the provisions of 37 CFR r SIX (6) MONTHS from the mailing date of this communication. e period for reply specified above is less than thirty (30) days, a r D period for reply is specified above, the maximum statutory periure to reply within the set or extended period for reply will, by stated the reply received by the Office later than three months after the material patent term adjustment. See 37 CFR 1.704(b).	N. 1.136 (a). In no event, however reply within the statutory minimulod will expire SIX tute. cause the application to be	may a reply be time of thirty (30) days to (6) MONTHS from the	ely filed will be considered time e mailing date of this (35.U.S.C. & 133)	aly. communication.				
1)⊠	Responsive to communication(s) filed on 2	1 February 2001 .							
2a)□	This action is FINAL . 2b)⊠	This action is non-final	•						
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.								
Disposit	ion of Claims		•						
4)⊠	4)⊠ Claim(s) <u>1-30 and 32-39</u> is/are pending in the application.								
	4a) Of the above claim(s) <u>29 and 30</u> is/are withdrawn from consideration.								
5)⊠	_								
6)⊠	6)⊠ Claim(s) <u>1-3, 6-11,33 and 35-39</u> is/are rejected.								
7)⊠	')⊠ Claim(s) <u>4, 5 and 34</u> is/are objected to.								
8)[Claims are subject to restriction and	or election requiremen	nt.						
Applicat	ion Papers			•					
9)	The specification is objected to by the Exam	iner.							
10)	The drawing(s) filed on is/are objecte	d to by the Examiner.							
11)	The proposed drawing correction filed on	is: a)□ approved	b) disappro	oved.					
12)									
Priority (under 35 U.S.C. § 119								
13)	Acknowledgment is made of a claim for forei	gn priority under 35 U.	S.C. ≶ 119(a)-	(d) or (f).					
	☐ All b)☐ Some * c)☐ None of:			(4) 5. (.).					
ŕ	1. Certified copies of the priority docume	nts have been receive	d.						
	2. Certified copies of the priority docume			ı No					
	3. Copies of the certified copies of the pr				Stage				
* 6	application from the International E See the attached detailed Office action for a li	Bureau (PCT Rule 17.2	?(a)).						
	Acknowledgement is made of a claim for dor	•							
Attachmen	t(s)								
6) 🔲 Noti	ice of References Cited (PTO-892) ice of Draftsperson's Patent Drawing Review (PTO-948) rmation Disclosure Statement(s) (PTO-1449) Paper No(s	19) 🗍 No		(PTO-413) Paper N atent Application (P					

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DETAILED ACTION

Continued Prosecution Application

1. The request filed on February 21, 2001 for a Continued Prosecution Application (CPA) under 37 CFR 1.53(d) based on parent Application No. 14 is acceptable and a CPA has been established. An action on the CPA follows.

Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 1, 2, 3, 7, 8, 9, 10, 11, 28, 35, 36, 37, 38 and 39 are rejected under 35

 U.S.C. 103(a) as being unpatentable over Tsai, U.S. Patent 5,235,204 in view of Wolf,

 "Silicon Processing For The VLSI ERA", vol. 2 (Process Integration), Lattice Press, 1990,

 pp. 116-117 & 126-127.
- 4. Pertaining to claims, 1, 7, 8, 9, 10, 28, 35, 36, 37, 38 and 39, <u>Tsai</u> discloses a semiconductor process substantially as claimed. See **FIG. 6**, where a method of making an emitter contact for an emitter region of a bipolar transistor is disclosed. <u>Tsai</u> discloses a polysilicon structure **60** over an emitter region position of a semiconductive substrate (not numbered). However, the metal emitter contact is not cross-diffused for a portion of the polysilicon structure to produce a metal emitter contact entirely above the surface of the substrate at the emitter region position. <u>Wolf</u> teaches the use of a doped polysilicon sacrificial barrier in the fabrication of contacts and interconnects (pp. 126). A thin layer of

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doped polysilicon can be used to separate the Al and the single-crystal Si substrate (Fig. 3-

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28). After the Al:Si alloy film as been patterned, the contact structure is annealed (pp. 127). In view of Wolf, it would have been obvious to one of ordinary skill in the art to cross-

diffused a portion of the polysilicon into the metal emitter contact of <u>Tsai</u> because this

process alleviates the problem of junction spiking (pp. 116).

5. Pertaining to claim 2, <u>Tsai</u> discloses an emitter region 40 as seen in **FIG. 6**. However, in the absence of new or unexpected results, the mere reversal of the order of performing process steps has been held to be prima facie obvious. In re Burhans, 154 F.2d 690, 69 USPQ 330 (CCPA

1946).

- 6. Pertaining to claim 3, <u>Tsai</u> discloses that the emitter region 40 is polysilicon and metallurgy level being aluminum which is obviously a doped layer (p-type) that will outdiffuse into the polysilicon region when annealed.
- 7. Pertaining to claim 11, <u>Tsai</u> discloses that the metal layer 64, can be aluminum.
- 8. Claim 6 is rejected under 35 U.S.C. 103(a) as being unpatentable over Tsai, U.S. Patent 5,235,204 in view of Wolf, "Silicon Processing For The VLSI ERA", vol. 2 (Process Integration), Lattice Press, 1990, pp. 116-117 & 126-127, as applied to claims 1-3 and 7-11 above, and further in view of Aboelfotoh et 1., U.S. Patent 5,801,444.
- 9. The combined teachings of Tsai in view of Wolf discloses a semiconductor process substantially as claimed as discussed above. However the combined teachings fail to

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disclose a polysilicon layer that includes polysilicon and germanium. Aboelfotoh discloses a semiconductor process wherein germanium is included with silicon for the purpose of making electrical contacts. See FIG. 11, where germanium (11) is deposited with polysilicon for the purposes of a contact for a semiconductor device. In view of Aboelfotoh it would have been obvious to one of ordinary skill in the art to include germanium with polysilicon for contact formation because a substantial advantage to be gained is that electrically stable contact metallization (column 5, lines 49-51).

- 10. Claims 4, 5 and 34 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.
- 11. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Takakura et al., JP 5-62925; IBM-TDB No. NN85091442; Neudeck et al., U.S. Patent 5,118,634 and Watanabe, U.S. Patent 4,987,562.

Allowable Subject Matter

- 12. Claims 12-27 and 32 allowed.
- The following is an examiner's statement of reasons for allowance: prior art does not teach a method of forming a polysilicon structure on an emitter region position of the transistor, the polysilicon structure including a doped diffusion barrier layer on the emitter region position and a polysilicon layer on the diffusion barrier layer; depositing metal including at least one of aluminum, gold, and silver on the polysilicon layer; and heating at least the deposited metal and the polysilicon structure to urge diffusion of the deposited metal

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Into the polysilicon layer, with the doped diffusion barrier layer inhibiting diffusion of the deposited metal into the emitter region of the transistor.

14. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

15. Any inquiry concerning this communication or earlier communications from the examiner should be directed to W. David Coleman whose telephone number is 703-305-0004. The examiner can normally be reached on 9:00 AM-5:00 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael M. Fahmy can be reached on 703-308-4918. The fax phone numbers for the organization where this application or proceeding is assigned are 703-308-7722 for regular communications and 703-308-7721 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

WDC May 5, 2001

PHINASTY EXAMINER